

Title (en)
SURFACE-MOUNTED SEMICONDUCTOR COMPONENT AND METHOD FOR THE PRODUCTION THEREOF

Title (de)
OBERFLÄCHENMONTIERBARES HALBLEITERBAUELEMENT UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)
COMPOSANT A SEMICONDUCTEUR POUR MONTAGE EN SURFACE ET PROCEDE DE FABRICATION

Publication
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Application
EP 03787632 A 20030707

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Abstract (en)
[origin: WO2004017407A1] Disclosed is a surface-mounted semiconductor component comprising a semiconductor chip (1), at least two external electrical connections (3, 4) that are connected in an electrically conducting manner to at least two electrical contacts of the semiconductor chip (1), and a chip cover (5). The two external electrical connections (3, 4) are disposed on a film (2) having a thickness of no more than 100 nm. The semiconductor chip (1) is fixed to a first main surface (22) of the film (2) while the chip cover (5) is applied to said first main surface (22). Also disclosed is a method for producing such a component.

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IPC 8 full level
H01L 23/12 (2006.01); **H01L 21/56** (2006.01); **H01L 23/31** (2006.01); **H01L 23/48** (2006.01); **H01L 23/495** (2006.01); **H01L 23/498** (2006.01); **H01L 33/48** (2010.01); **H01L 33/62** (2010.01)

CPC (source: EP US)
H01L 21/561 (2013.01 - EP US); **H01L 21/565** (2013.01 - EP US); **H01L 23/3121** (2013.01 - EP US); **H01L 23/49838** (2013.01 - EP US); **H01L 23/4985** (2013.01 - EP US); **H01L 24/97** (2013.01 - EP US); **H01L 33/486** (2013.01 - EP US); **H01L 33/62** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/05599** (2013.01 - EP US); **H01L 2224/45099** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/85399** (2013.01 - EP US); **H01L 2224/97** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01004** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01015** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01032** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01061** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01075** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/01084** (2013.01 - EP US); **H01L 2924/12041** (2013.01 - EP US); **H01L 2924/12042** (2013.01 - EP US); **H01L 2924/12043** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US)

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